# **Switch Mode Power Rectifiers**

16 A, 35 and 45 V

These state-of-the-art devices use the Schottky Barrier principle with a platinum barrier metal.

#### **Features**

- Guard-ring for Stress Protection
- Low Forward Voltage
- 175°C Operating Junction Temperature
- NRVB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

### **Mechanical Characteristics:**

- Case: Epoxy, Molded
- Weight: 1.9 Grams for TO-220
  - 1.7 Grams for D<sup>2</sup>PAK
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Max. for 10 Seconds

#### **MAXIMUM RATINGS**

| Rating  | Symbol   | Value          | Unit |
|---|--|----------------|------|
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage MBR1635 MBR1645 MBRB1645                           | V <sub>RRM</sub><br>V <sub>RWM</sub><br>V <sub>R</sub> | 35<br>45<br>45 | V    |
| Average Rectified Forward Current Delay (Rated V <sub>R</sub> , T <sub>C</sub> = 163°C) Total Device                                | I <sub>F(AV)</sub>                                     | 16             | Α    |
| Peak Repetitive Forward Current, Per<br>Leg<br>(Rated V <sub>R</sub> , Square Wave,<br>20 kHz, T <sub>C</sub> = 157°C) Total Device | I <sub>FRM</sub>                                       | 32             | Α    |
| Non-Repetitive Peak Surge Current<br>(Surge Applied at Rated Load Conditions<br>Halfwave, Single Phase, 60 Hz)                      | I <sub>FSM</sub>                                       | 150            | Α    |
| Peak Repetitive Reverse Surge Current (2.0 μs, 1.0 kHz)   | I <sub>RRM</sub>                                       | 1.0            | Α    |
| Storage Temperature Range   | T <sub>stg</sub>                                       | -65 to +175    | °C   |
| Operating Junction Temperature (Note 1)   | $T_J$  | -65 to +175    | °C   |
| Voltage Rate of Change (Rated V <sub>R</sub> )  | dv/dt  | 10,000         | V/μs |

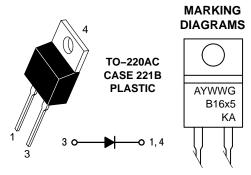
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. The heat generated must be less than the thermal conductivity from Junction-to-Ambient:  $dP_D/dT_J < 1/R_{\theta,JA}$ .



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= Assembly Location

Y = Year

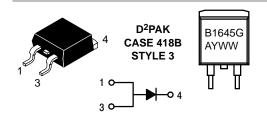
WW = Work Week

B16x5 = Device Code

x = 3 or 4

KA = Diode Polarity

G = Pb-Free Package



B1645 = Device Code A = Assembly Location

Y = Year
WW = Work Week
G = Pb-Free Package

### **ORDERING INFORMATION**

| 0112211110 1111 011111111111 |                                 |                  |  |
|------------------------------|---------------------------------|------------------|--|
| Device                       | Package                         | Shipping         |  |
| MBR1635G                     | TO-220<br>(Pb-Free)             | 50 Units / Rail  |  |
| MBR1645G                     | TO-220<br>(Pb-Free)             | 50 Units / Rail  |  |
| MBRB1645T4G                  | D <sup>2</sup> PAK<br>(Pb-Free) | 800 Units / Rail |  |
| NRVBB1645T4G                 | D <sup>2</sup> PAK<br>(Pb-Free) | 800 Units / Rail |  |

### THERMAL CHARACTERISTICS

| Characteristic              |                  | Symbol         | Value | Unit |
|-----------------------------|------------------|----------------|-------|------|
| Maximum Thermal Resistance, | Junction-to-Case | $R_{	heta JC}$ | 1.5   | °C/W |

### **ELECTRICAL CHARACTERISTICS**

| Characteristic  | Symbol         | Value        | Unit |
|---|----------------|--------------|------|
| Maximum Instantaneous Forward Voltage (Note 2)<br>( $i_F = 16 \text{ Amps}, T_C = 125^{\circ}\text{C}$ )<br>( $i_F = 16 \text{ Amps}, T_C = 25^{\circ}\text{C}$ ) | VF             | 0.57<br>0.63 | V    |
| Maximum Instantaneous Reverse Current (Note 2) (Rated dc Voltage, $T_C = 125^{\circ}C$ ) (Rated dc Voltage, $T_C = 25^{\circ}C$ )                                 | i <sub>R</sub> | 40<br>0.2    | mA   |

<sup>2.</sup> Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤ 2.0%.

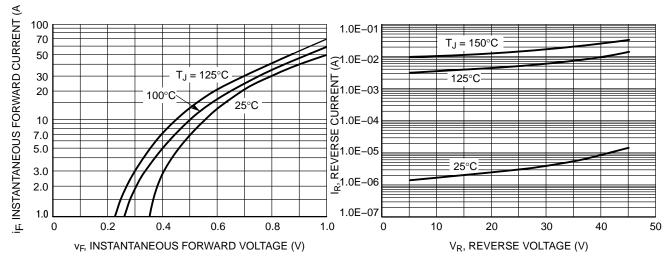


Figure 1. Typical Forward Voltage

**Figure 2. Typical Reverse Current** 

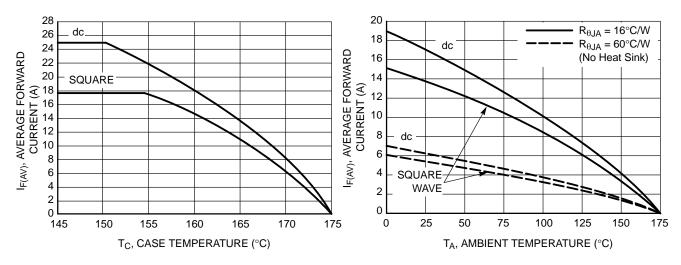


Figure 3. Current Derating, Case, Per Leg

Figure 4. Current Derating, Ambient

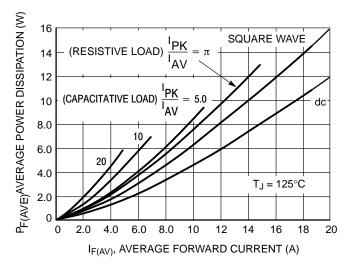
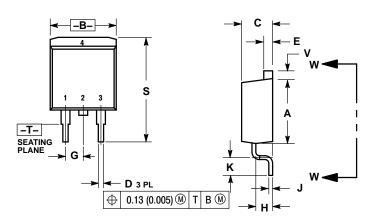
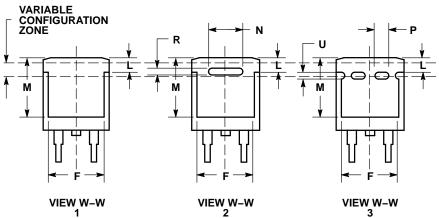


Figure 5. Forward Power Dissipation

### **PACKAGE DIMENSIONS**

### D<sup>2</sup>PAK CASE 418B-04 **ISSUE J**





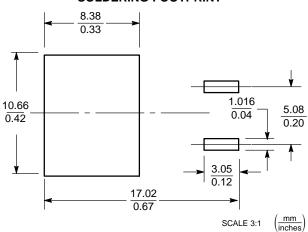
- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. 418B-01 THRU 418B-03 OBSOLETE, NEW STANDARD 418B-04.

|     | INCHES    |       | MILLIMETERS |       |
|-----|-----------|-------|-------------|-------|
| DIM | MIN       | MAX   | MIN         | MAX   |
| Α   | 0.340     | 0.380 | 8.64        | 9.65  |
| В   | 0.380     | 0.405 | 9.65        | 10.29 |
| С   | 0.160     | 0.190 | 4.06        | 4.83  |
| D   | 0.020     | 0.035 | 0.51        | 0.89  |
| E   | 0.045     | 0.055 | 1.14        | 1.40  |
| F   | 0.310     | 0.350 | 7.87        | 8.89  |
| G   | 0.100 BSC |       | 2.54 BSC    |       |
| Н   | 0.080     | 0.110 | 2.03        | 2.79  |
| J   | 0.018     | 0.025 | 0.46        | 0.64  |
| K   | 0.090     | 0.110 | 2.29        | 2.79  |
| L   | 0.052     | 0.072 | 1.32        | 1.83  |
| M   | 0.280     | 0.320 | 7.11        | 8.13  |
| N   | 0.197 REF |       | 5.00 REF    |       |
| Р   | 0.079 REF |       | 2.00 REF    |       |
| R   | 0.039 REF |       | 0.99 REF    |       |
| S   | 0.575     | 0.625 | 14.60       | 15.88 |
| V   | 0.045     | 0.055 | 1 14        | 1 40  |

### STYLE 3:

- PIN 1. ANODE 2. CATHODE 3. ANODE 4. CATHODE

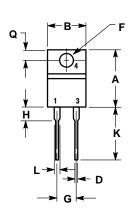
### **SOLDERING FOOTPRINT\***

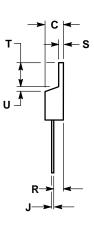


\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### PACKAGE DIMENSIONS

TO-220 CASE 221B-04 **ISSUE E** 





- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.

|     | INCHES |       |       | ETERS |
|-----|--------|-------|-------|-------|
| DIM | MIN    | MAX   | MIN   | MAX   |
| Α   | 0.595  | 0.620 | 15.11 | 15.75 |
| В   | 0.380  | 0.405 | 9.65  | 10.29 |
| С   | 0.160  | 0.190 | 4.06  | 4.82  |
| D   | 0.025  | 0.035 | 0.64  | 0.89  |
| F   | 0.142  | 0.161 | 3.61  | 4.09  |
| G   | 0.190  | 0.210 | 4.83  | 5.33  |
| Н   | 0.110  | 0.130 | 2.79  | 3.30  |
| J   | 0.014  | 0.025 | 0.36  | 0.64  |
| K   | 0.500  | 0.562 | 12.70 | 14.27 |
| L   | 0.045  | 0.060 | 1.14  | 1.52  |
| Q   | 0.100  | 0.120 | 2.54  | 3.04  |
| R   | 0.080  | 0.110 | 2.04  | 2.79  |
| S   | 0.045  | 0.055 | 1.14  | 1.39  |
| Т   | 0.235  | 0.255 | 5.97  | 6.48  |
| U   | 0.000  | 0.050 | 0.000 | 1.27  |

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